

Mask Aligner Process Enhancement by Spatial Filtering

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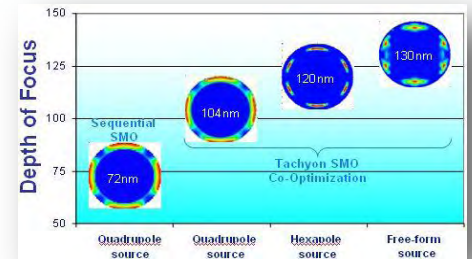
* vogler@suss.ch

Micro-Optics in Front-End Lithography

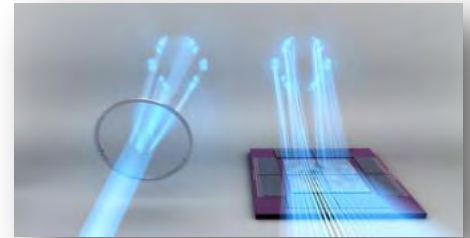


Customized Illumination
Pupil Shaping (DOE)
Now: FlexRay™
programmable illumination
technology from ASML

Excimer Laser (193nm)
Laser Beam Shaping
Laser Beam Homogenizing



Customized Illumination

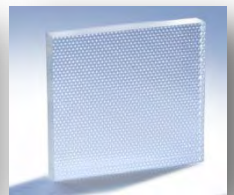
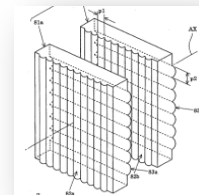


Diffractive Optical Elements (DOE)

MEMS Mirror Arrays (FlexRay™)



Micro-Optics is Key Enabling Technology in Front-End Lithography

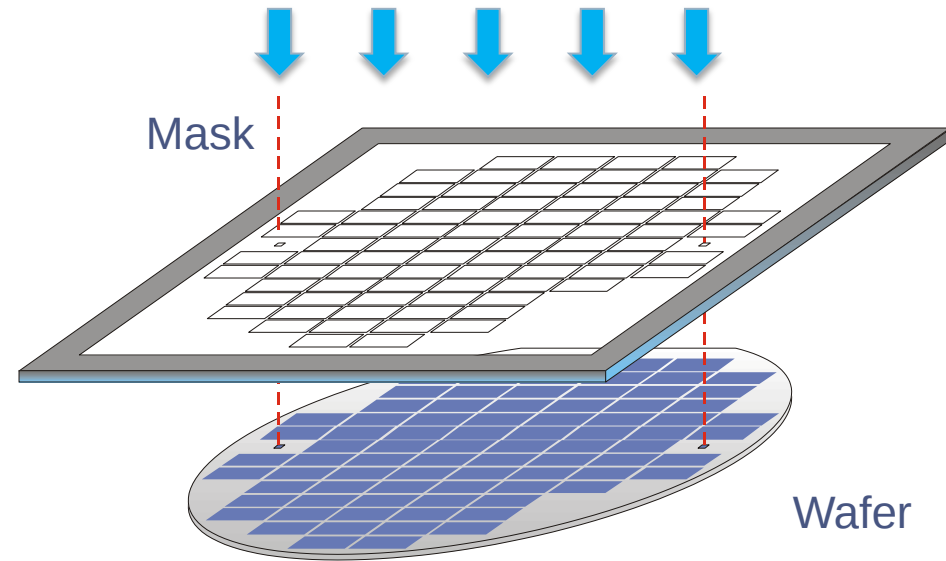


MicroLens Köhler Homogenizer

Back End Lithography: Mask Aligner

Mask Aligners Lithography is „Shadow Printing“

- + Mask illumination using UV light (High Pressure Mercury)
- + Resolution $\Leftrightarrow$ proximity gap



Mode	Gap (μm)	Min. Resolution
Contact	$\rightarrow 0$	$> \lambda$
Proximity	$10 < \text{gap} < 200$	$> \frac{3}{2} \sqrt{\lambda \bullet \left(\text{gap} + \frac{\text{ResistTh}}{2} \right)}$

Mask Aligner Lithography

All about illumination!

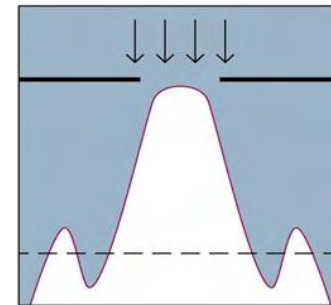
- + Diffraction effects
- + Partial coherence
- + Side lobes
- + Apodization



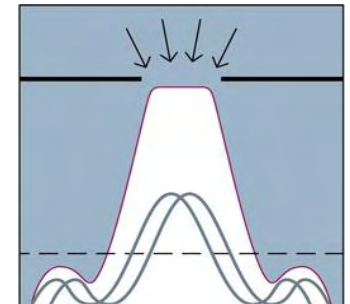
Parallel Light



Diffuse Light



Parallel Light



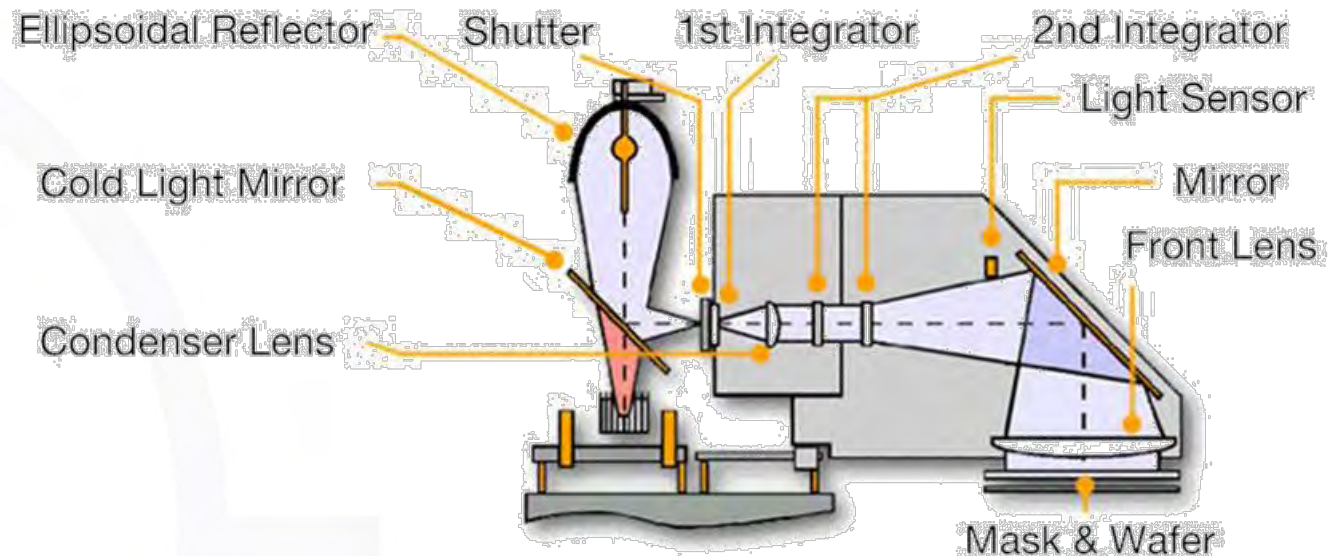
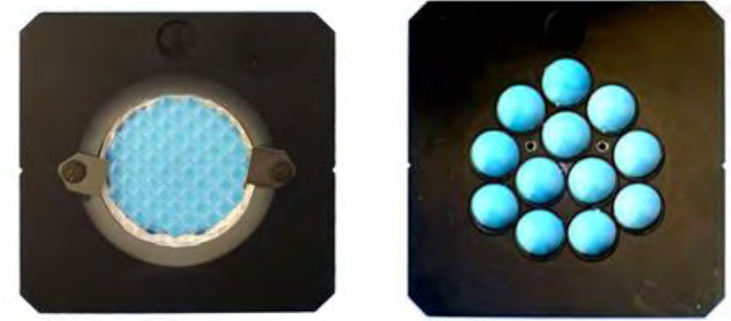
Apodization

Customized Illumination?

Mask Aligner Illumination System

Requirements

- + Good Uniformity < 3% (5%)
- + Max. irradiance intensity
- + Long term stability
- + Diffraction reduction

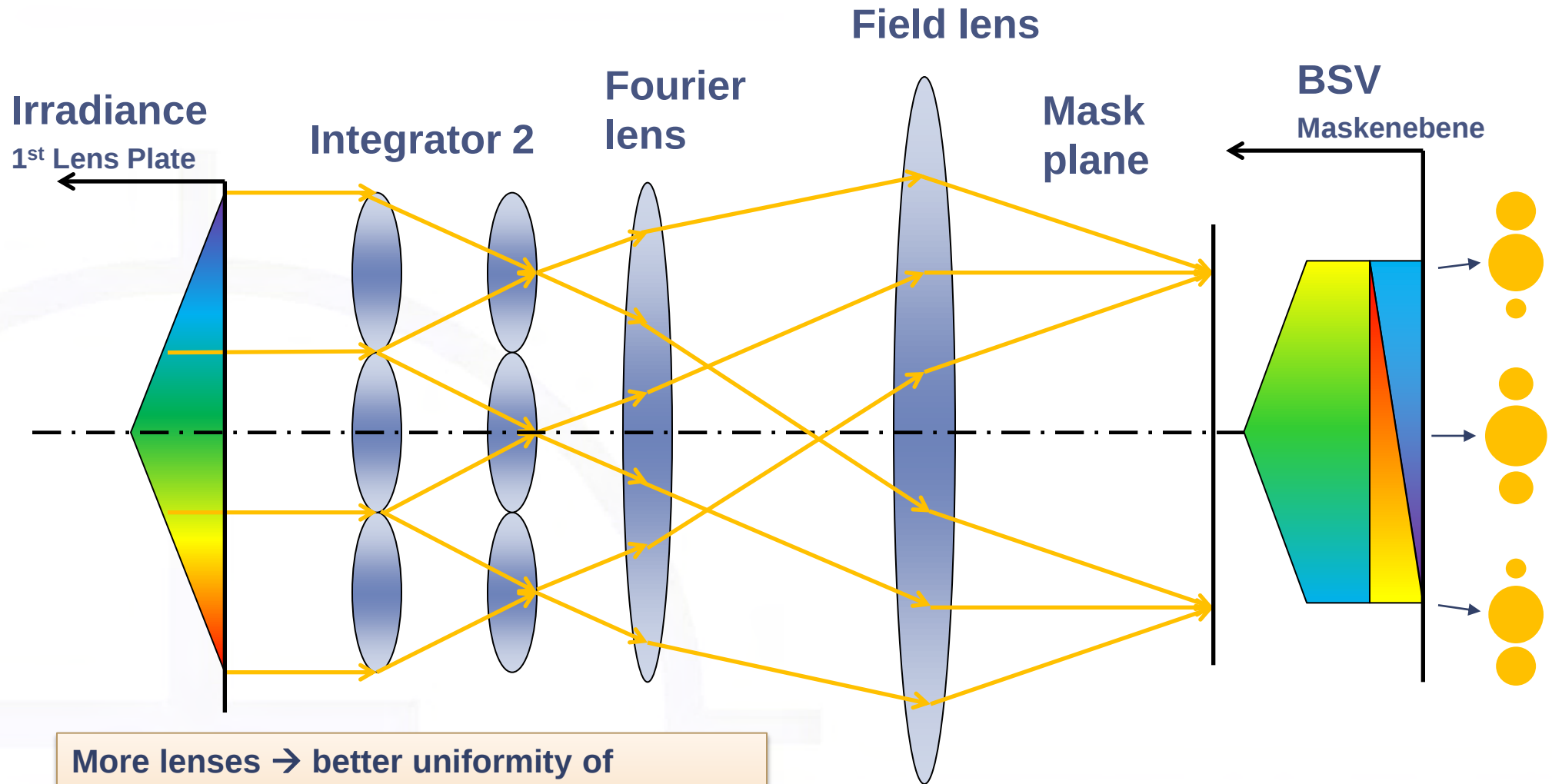


Standard Mask Aligner Illumination System

Feature

- + Off-axis Illumination
- + fixed illumination angles

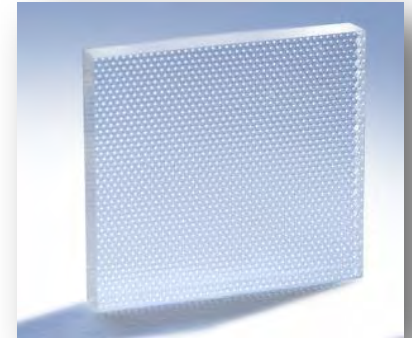
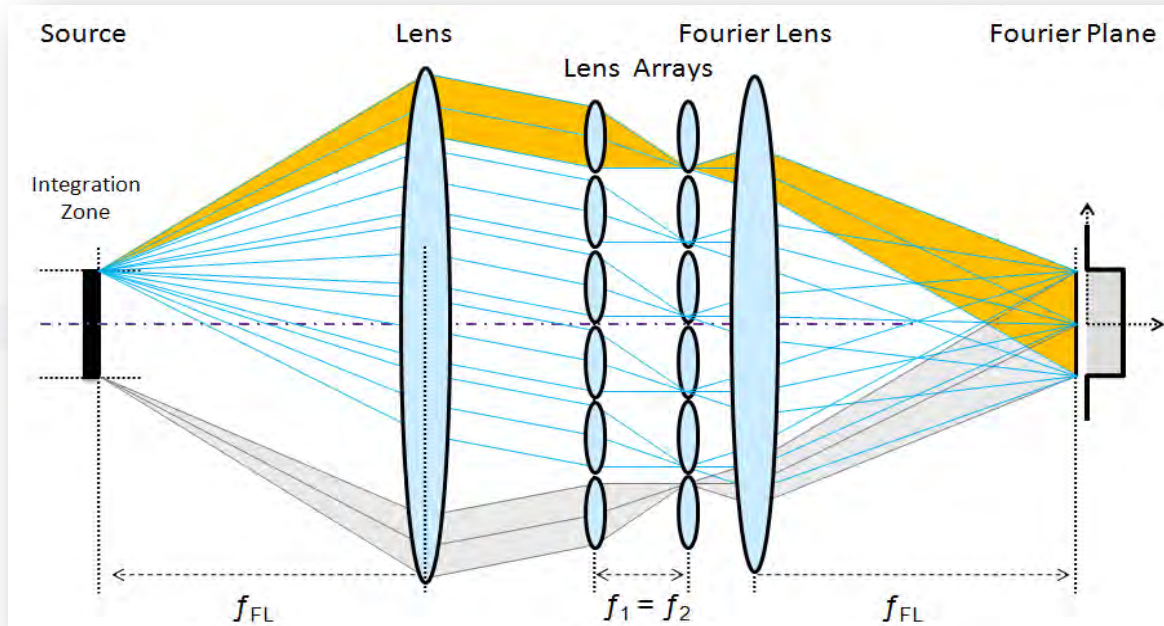
Mask Illumination



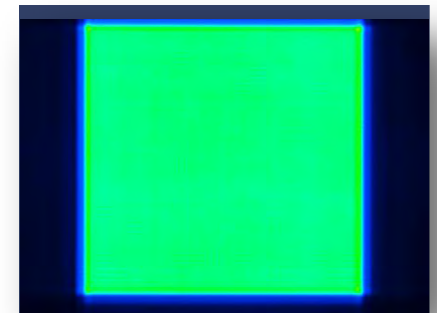
More lenses → better uniformity of

- Irradiance intensity
- Angular spectrum

Microlens Optical Integrator (Köhler)



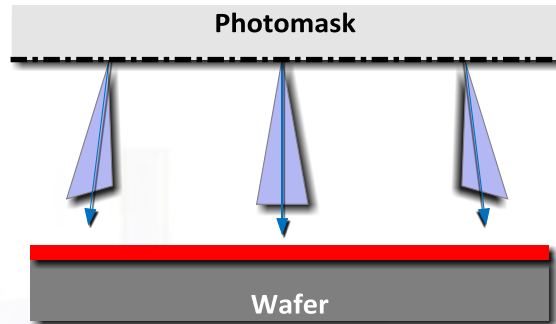
Microlens Array



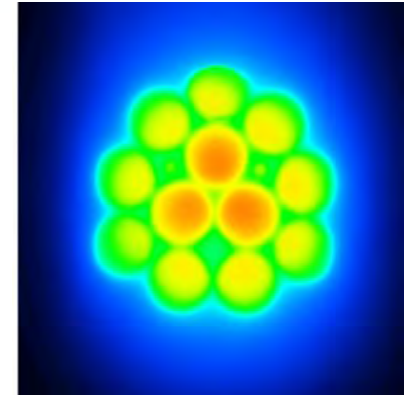
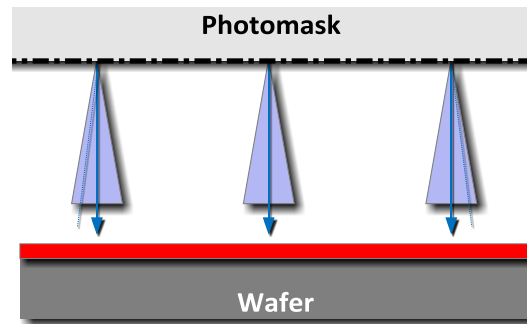
Flat-Top Intensity Profile

Microlens Arrays → Stability / Telecentricity

Standard Mask Illumination



Telecentric Mask Illumination



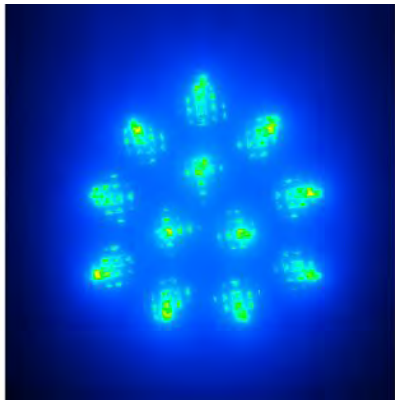
Uniform angular spectrum over the entire mask plane

Features

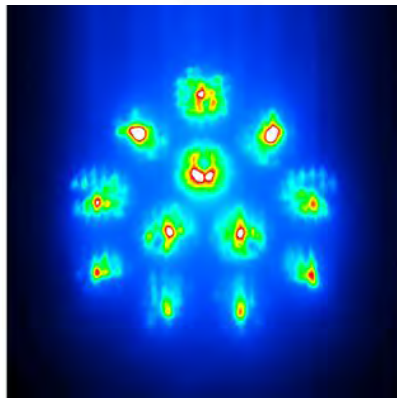
- + Stable Light Source
- + Excellent Uniformity
- + Telecentric Illumination

Benefits

- + Reduced Maintenance
- + Improved CD Uniformity
- + Larger Process Window
- + Higher Yield



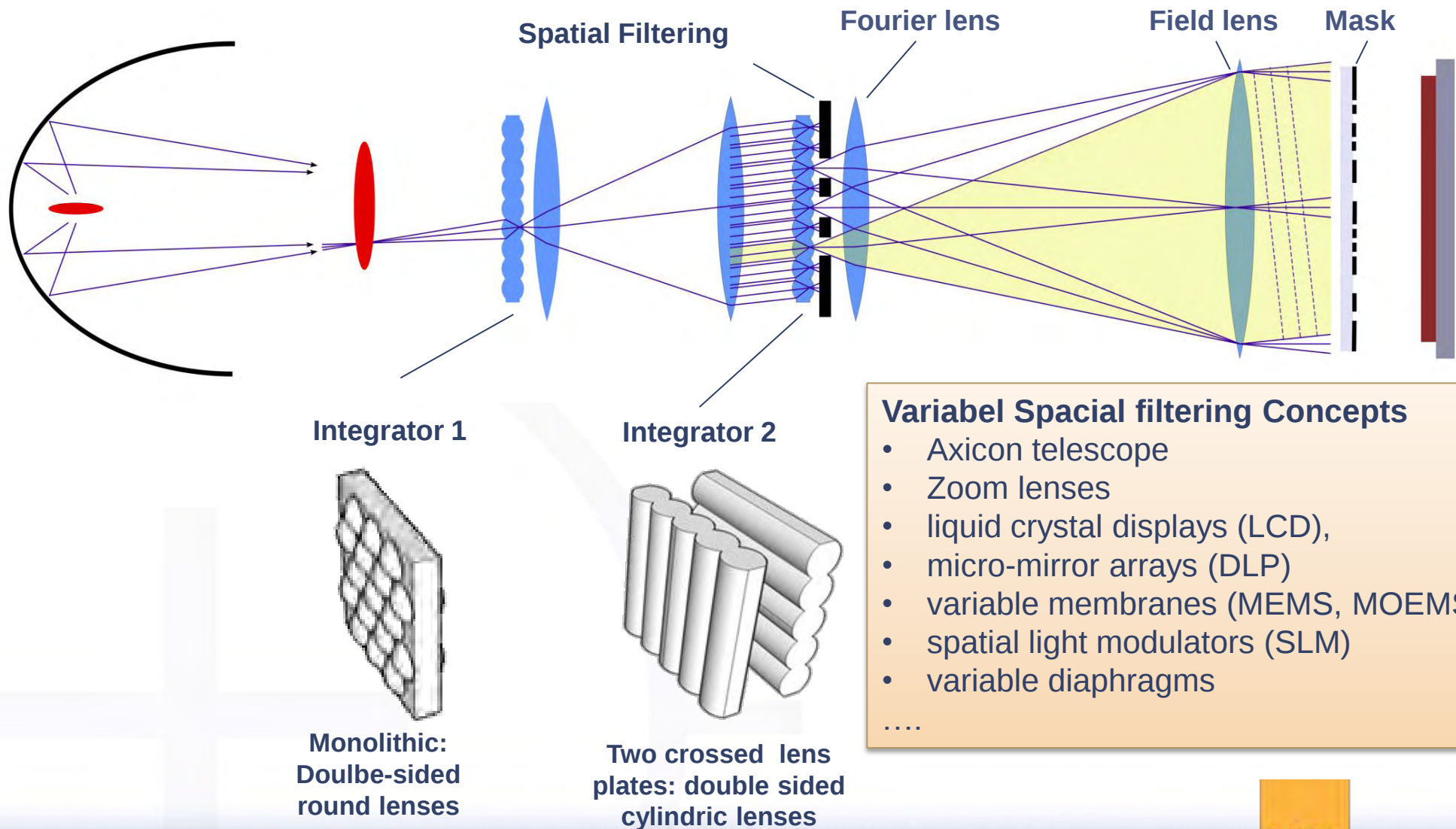
centre



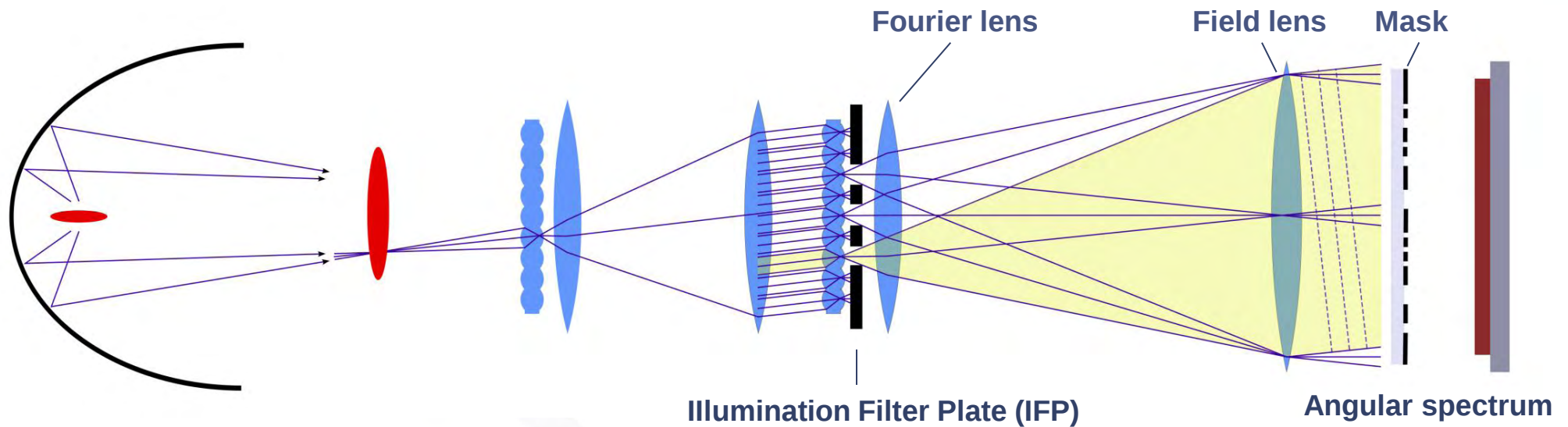
rim

Angular spectrum at the mask plane

Funktion IFP's



Illumination Filter Plates (IFP's)

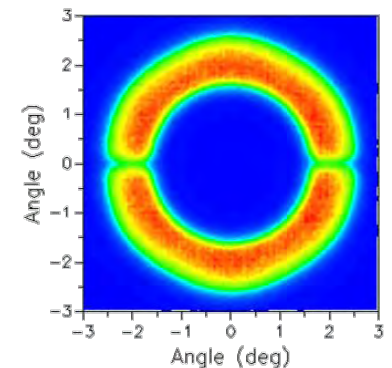


IFP's

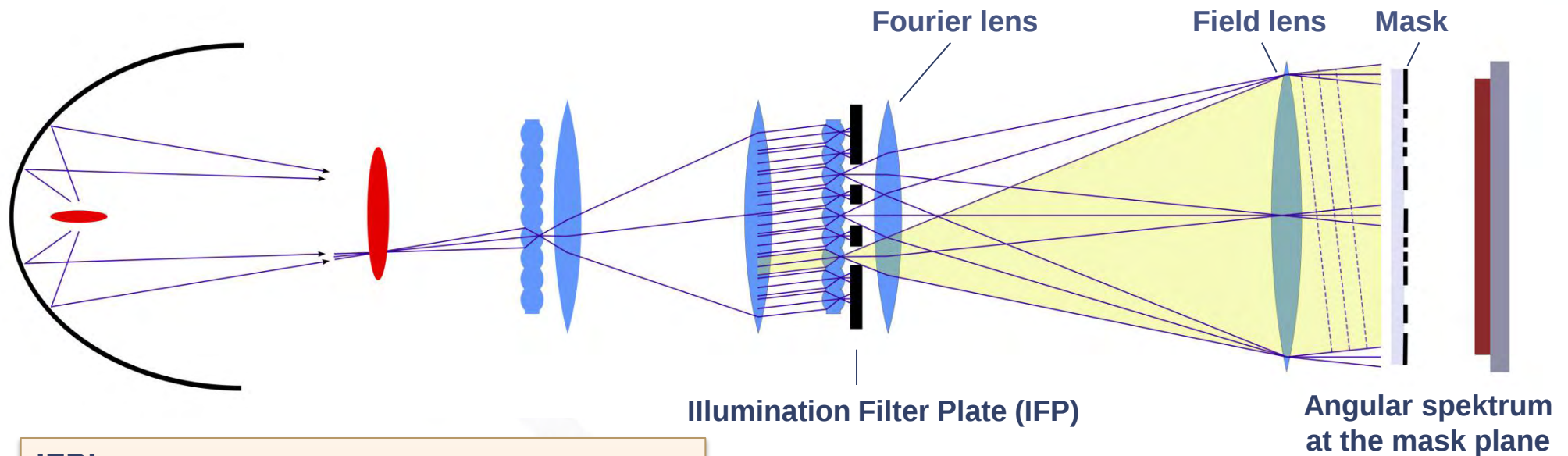
- Free form illumination
- Quick and easy changeover
- Self-made customized illumination
- Long term stability
- Downward compatible (no software modifications)



Angular spectrum at the mask plane

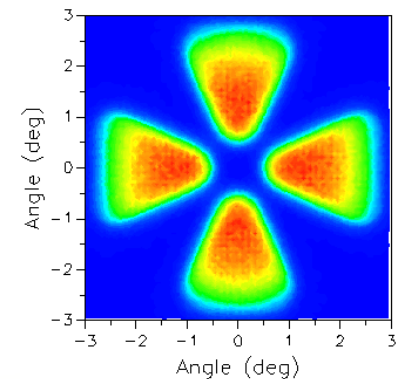


Illumination Filter Plates (IFP's)

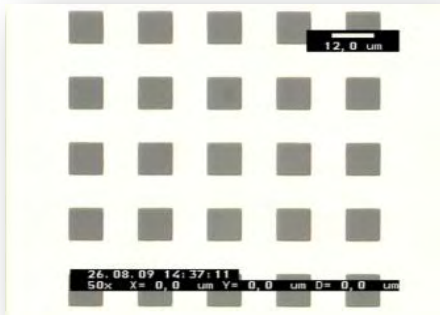


IFP's

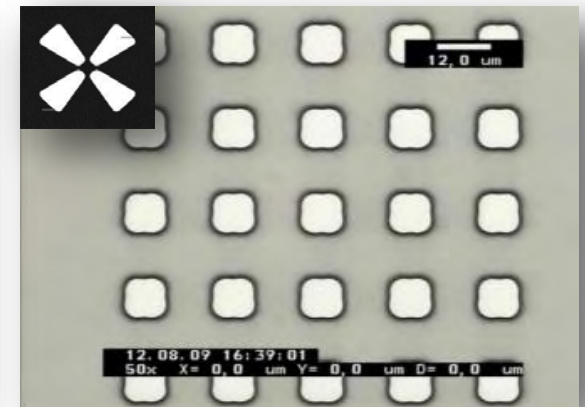
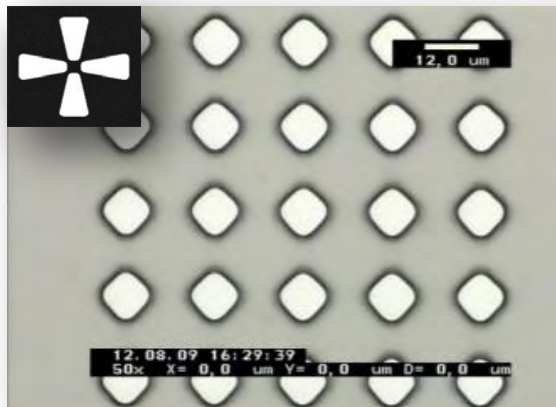
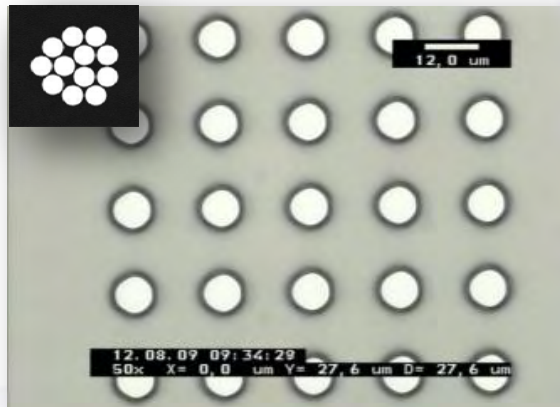
- Free form illumination
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Customized Illumination - Optimize Pattern

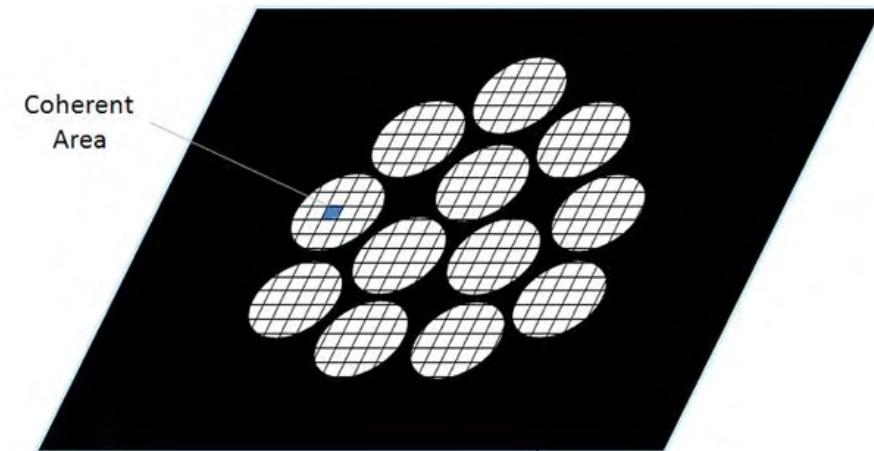
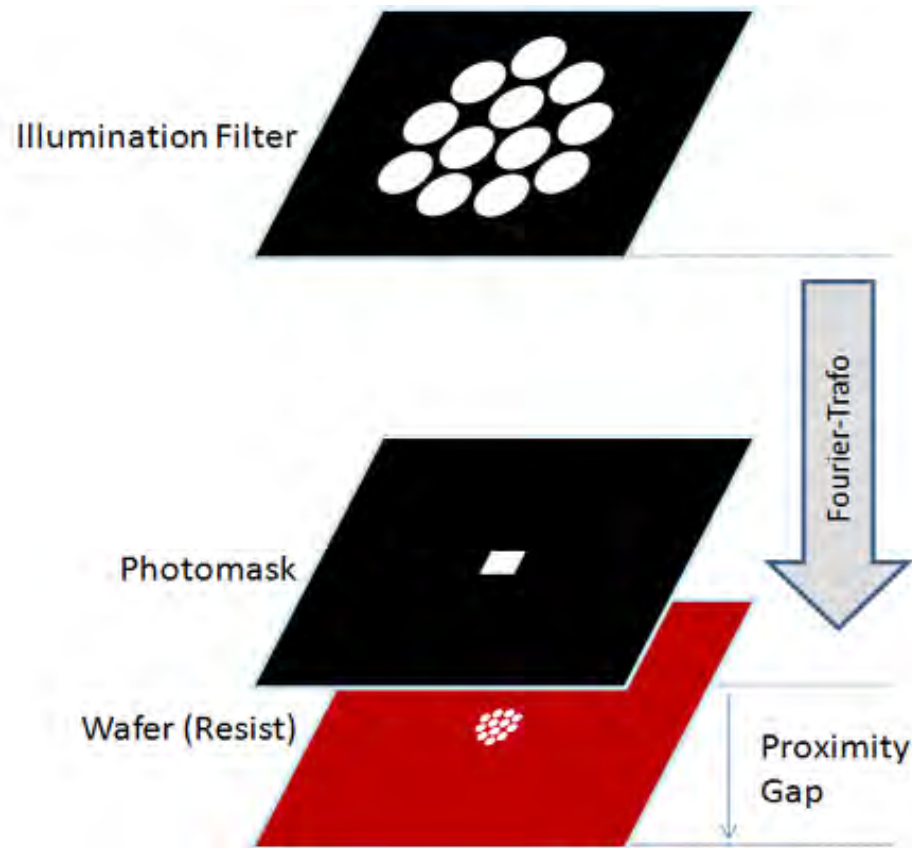


Photomask Pattern
Square $10 \times 10 \mu\text{m}^2$

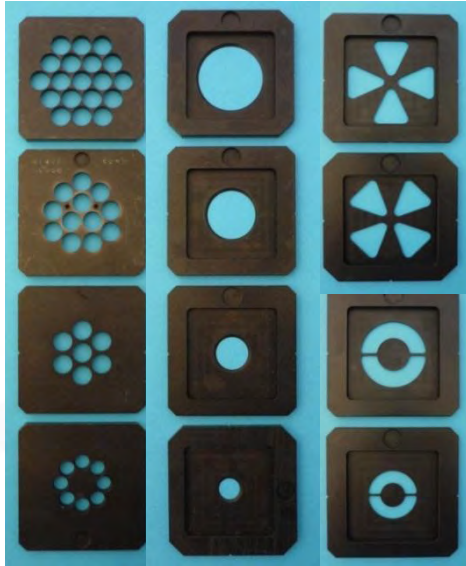


Prints in Photoresist, 1.2μm thick resist (AZ 4110), 100μm Proximity Gap, SUSS MA8

Image formation



IFPs: Trail or calculation?



Evaluation of the perfect in the laboratory can consume a lot of resources.

Simulation needed for the preselection of illumination settings.



A stable, telecentric illumination is needed to get reliable simulation results

Challenges:

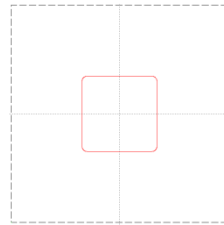
- + Calculation time for big areas
- + Analyses of resist parameters
- + Stability of resist parameters

Input

Mask Design

Amplitude
Phase

Mask design

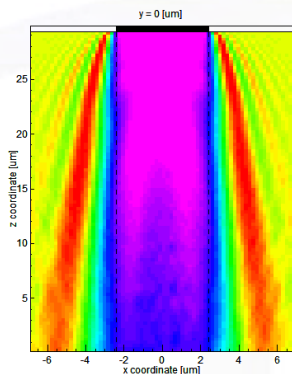


Stack configuration

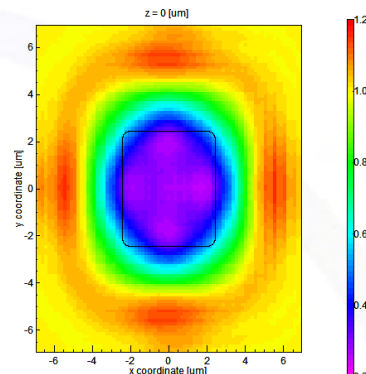
Substrate
Resist Parameter
Topography

Exposure Configuration

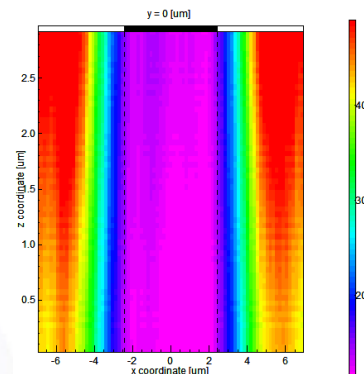
Wavelength spectrum
Gap
Angular spectrum



Cross section of the irradiance distribution within the gap



Aerial image on top of the resist



Cross section of irradiance in resist

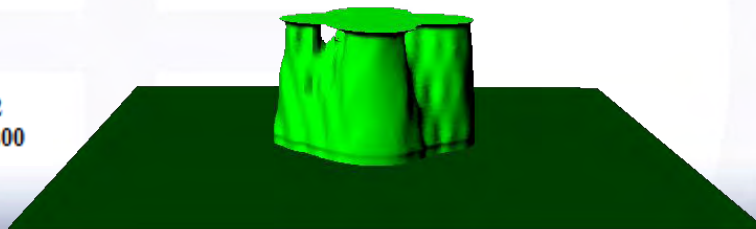
Intermediate Data

Aerial Image
3D-Energy Spread
Resist Image

Analyses Values

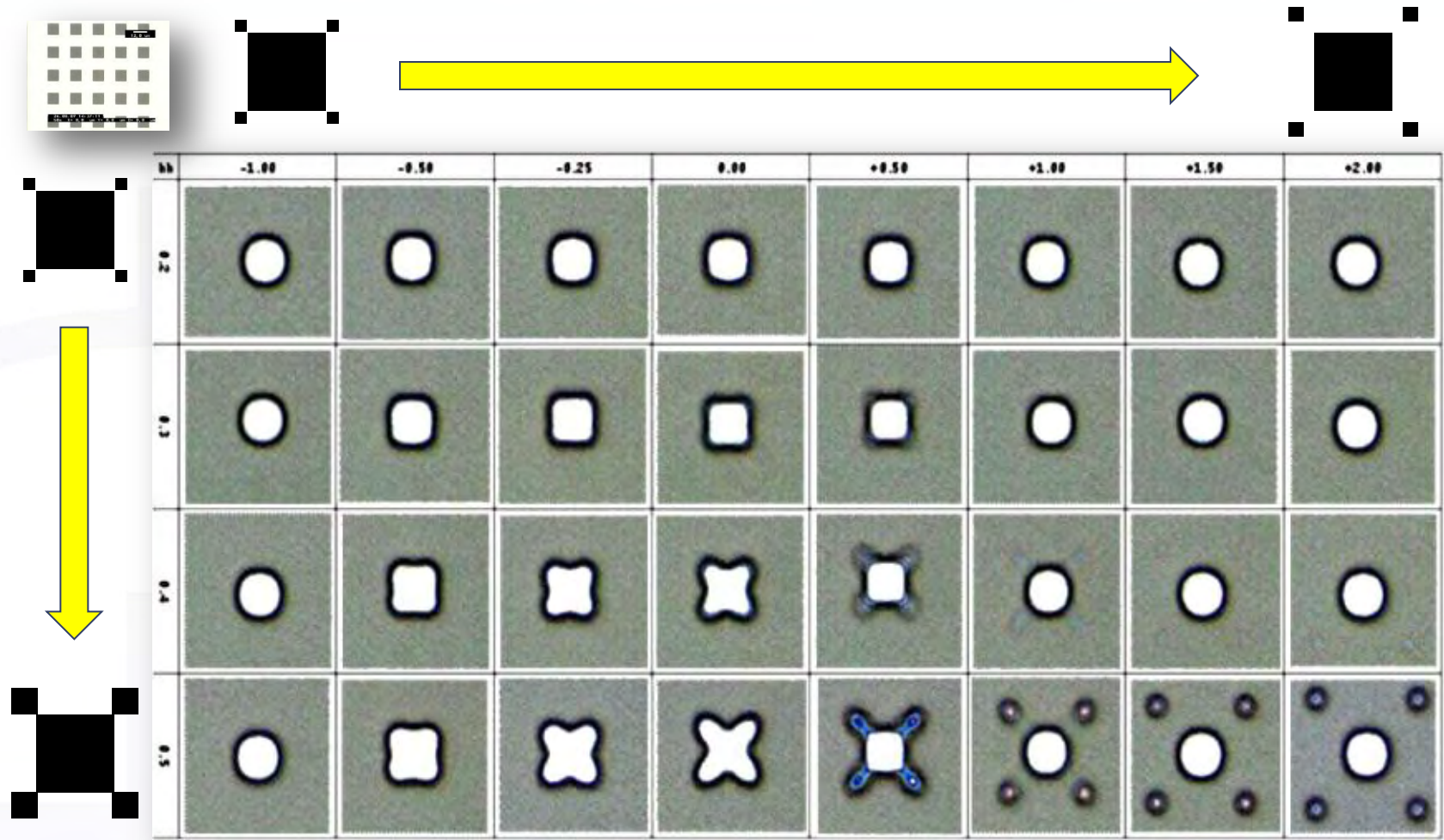
Process Window
Sidewall shape
CD vs. Gap
CD vs. Dose
Normalized Image Log Slope (N.I.L.S.)

SiO₂
AZ9200



3D- Image of the resulting resist cylinder

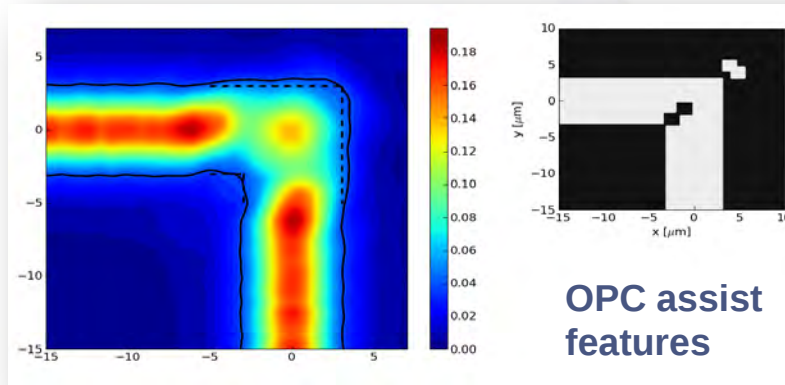
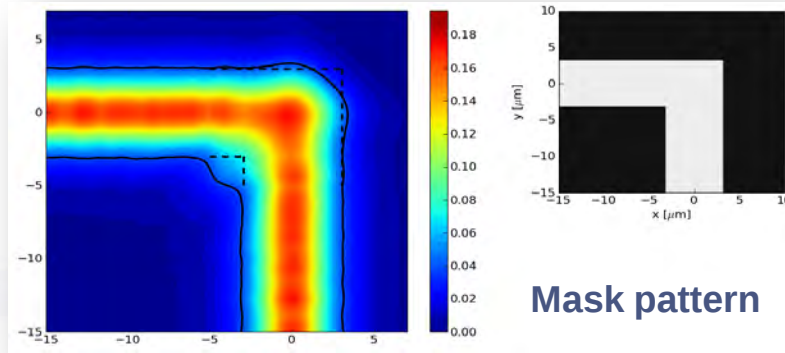
Source-Mask Optimization: Mask Optimization



Square 10µm x 10µm, Proximity Gap 50µm, Photoresist AZ4110, 1.2µm thick

Optical Proximity Correction (OPC)

Aerial image (simulation)



Ref: Kristian Motzek, FhG-IISB, SUSS Report Sept 2010

- 6µm line
- Aerial image
- 40µm Proximity gap
- OPC assist features

Source-Mask Optimization Service

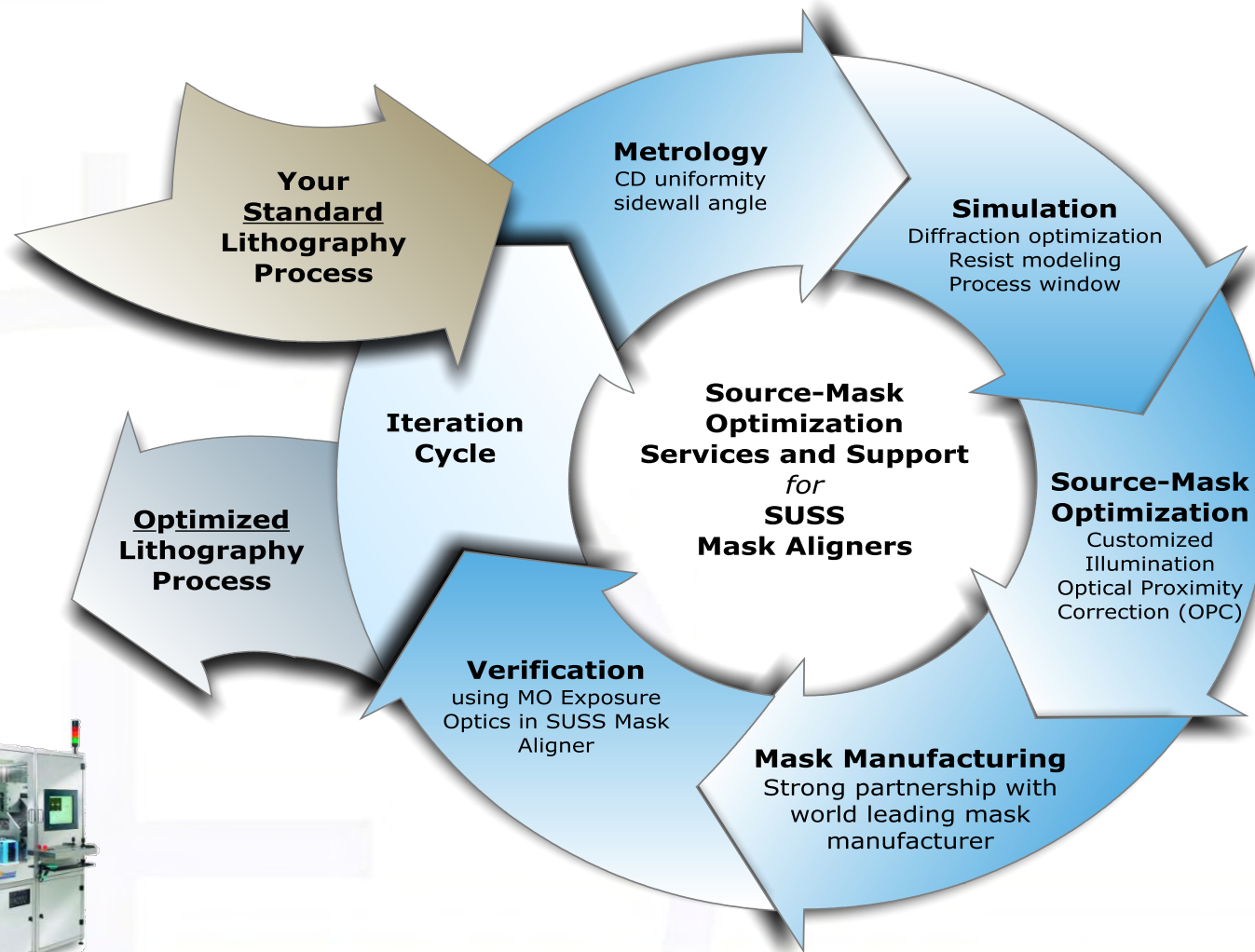


TOPPAN
TOPPAN PHOTOMASKS, INC.

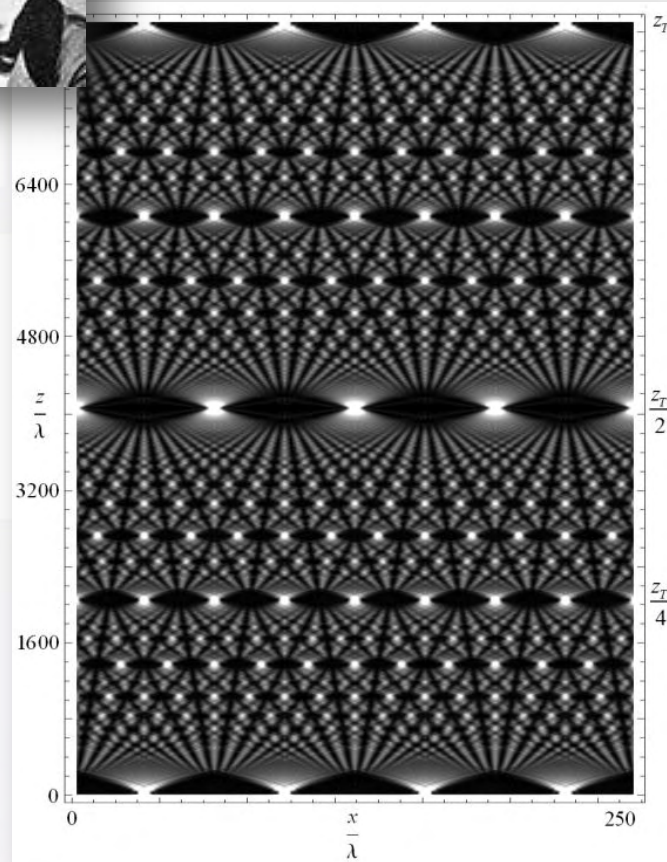
Fraunhofer
IISB



SUSS MicroOptics

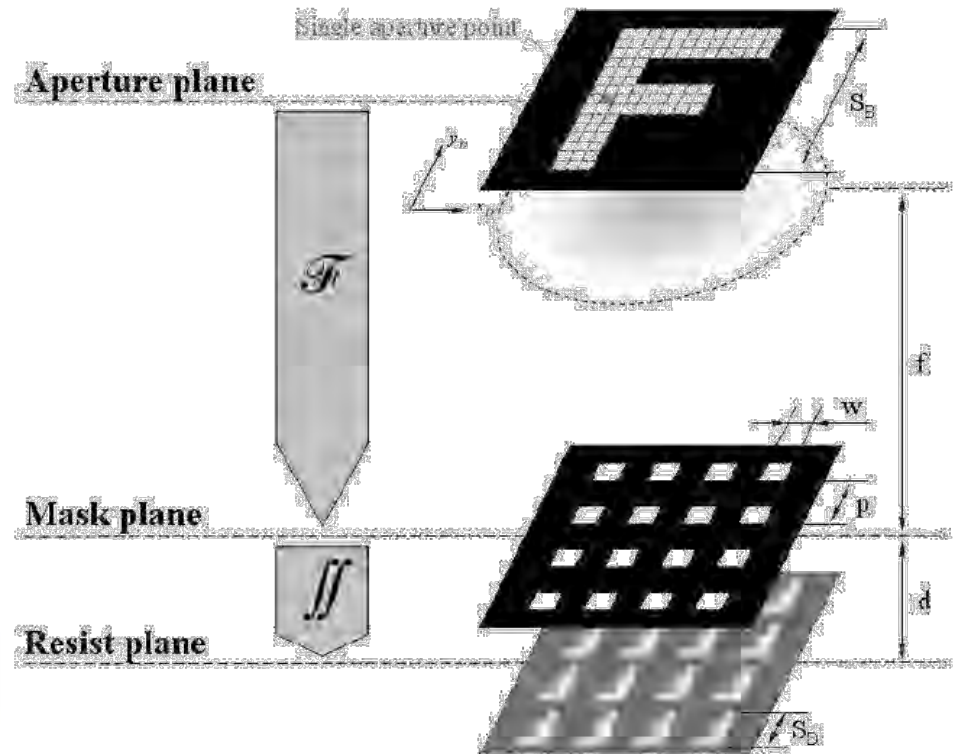


Application Example: Talbot effect



Talbot carpet

(Source: Ben Goodman, Wikipedia)



Application Example: Talbot Effect

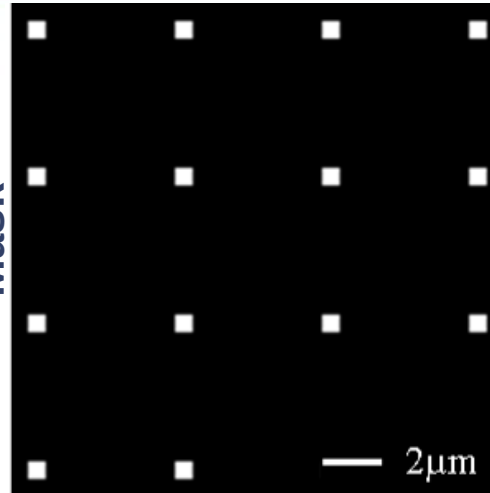
Features

- + For periodic structures
- + Information transfer for big gaps and small resolution

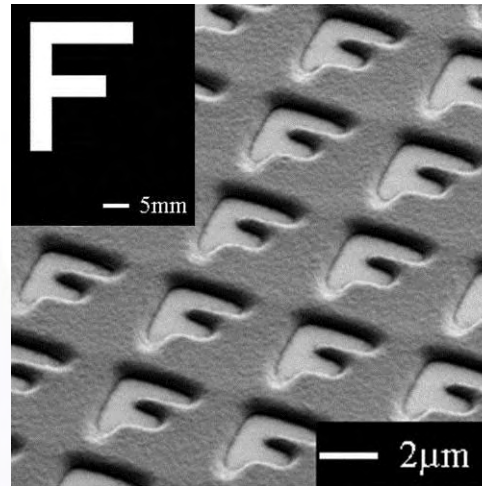


Simple pattern change with pixelated Illumination Filter Plate (IFP)

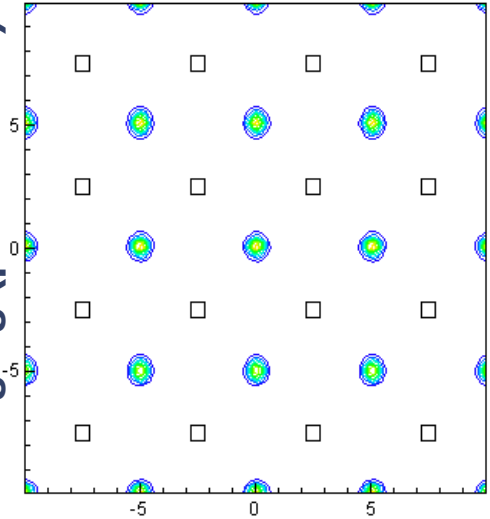
Mask



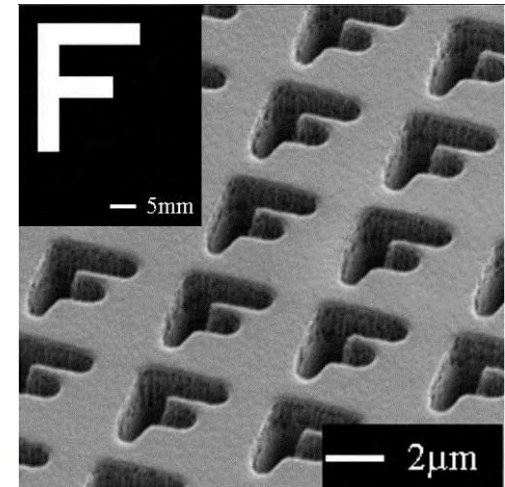
SEM Reist



Simulation of self imaging (pinhole IFP)



SEM after RIE



Grey-Level Structures Printed on Full Wafer in MA6

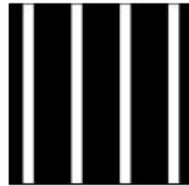
1D

Aperture



$S = 40\mu\text{m}$

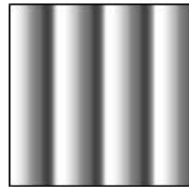
Mask



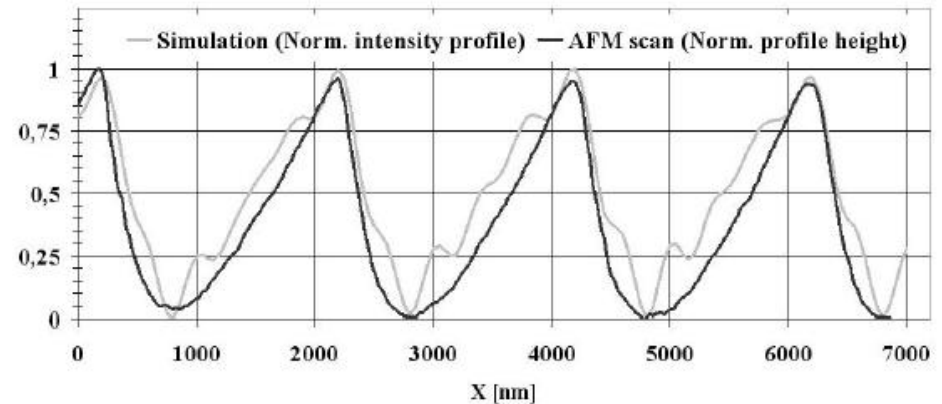
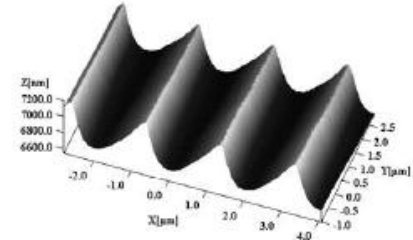
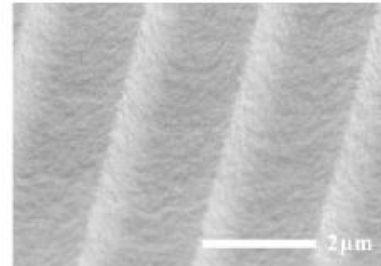
$p = 2\mu\text{m}; w = 450\text{nm}$

Proximity distance $d = 20,5\mu\text{m}$

Simulated Intensity



$S = 2\mu\text{m}$



SE micrograph and atomic force scan of a realized grating structure in photo resist AZ 4562. The normalized profile scan of the resist structure (height: 580nm) and the normalized intensity profile are shown together

Summary / Outlook

Summary

- + Increase of uniformity, telecentricity → higher yield
- + Enables lithography simulation
- + Enables Customized Illumination, Source-Mask-Optimization,

Outlook

- + Create further optimization rules

Acknowledgment



+ Torsten Harzendorf



+ Andreas Erdmann

+ Kristian Motzek



+ Kenneth Weible

+ Pascal Pernet

+ Arianna Bramati



Thank you for your attention!!

SUSS.

Our Solutions Set
Standards

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